

	U	I	Document ID	Issue Date	Pages	Title	Current OR	Current XRef
1	<input type="checkbox"/>	<input type="checkbox"/>	US 20040101991 A1	20040527	13	Microelectronic device packages and methods for controlling the disposition of	438/106	
2	<input type="checkbox"/>	<input type="checkbox"/>	US 20040005732 A1	20040108	14	MICROELECTRONIC DEVICE PACKAGES AND METHODS FOR CONTROLLING THE	438/105	
3	<input type="checkbox"/>	<input type="checkbox"/>	US 20030189262 A1	20031009	17	Method and apparatus for attaching microelectronic substrates and support	257/783	257/784
4	<input type="checkbox"/>	<input type="checkbox"/>	US 20030116861 A1	20030626	18	Multi-substrate microelectronic packages and methods for manufacture	257/778	257/E21.512; 257/E25.013
5	<input type="checkbox"/>	<input type="checkbox"/>	US 20030100200 A1	20030529	15	Buried solder bumps for AC-coupled microelectronic interconnects	439/66	
6	<input type="checkbox"/>	<input type="checkbox"/>	US 20030012868 A1	20030116	15	Method for dispensing flowable substances on microelectronic substrates	427/8	427/58
7	<input type="checkbox"/>	<input type="checkbox"/>	US 20020190396 A1	20021219	13	Method and apparatus for removing encapsulating material from a packaged	257/787	257/686; 257/713;
8	<input type="checkbox"/>	<input type="checkbox"/>	US 20020020898 A1	20020221	35	Microelectronic substrates with integrated devices	257/676	257/668; 257/701;
9	<input type="checkbox"/>	<input type="checkbox"/>	US 20010008357 A1	20010719	17	Methods of fabricating in-plane MEMS thermal actuators	310/306	
10	<input type="checkbox"/>	<input type="checkbox"/>	US 6750547 B2	20040615	15	Multi-substrate microelectronic packages and methods for manufacture	257/778	257/E21.508; 257/E23.069;
11			US 6680078 B2	20040120	15	Method for dispensing flowable substances	427/8	118/320